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To the Honorable Commissioner of Patents & Trademarks: Please record the attached original document(s) or copy thereof.

1. Name of conveying parties:  Tae Uk Kim, Hee Sook Na, and Duk Hee Kim	2. Name and address of receiving party(ies):  CHEIL INDUSTRIES INC 290 Gongdan-dong, Gumi-si, Gyeongsangbuk-do, 730-710 Seoul, Republic of Korea
3. Nature of conveyance: Assignment  Execution date: May 31, 2007	There are no additional names or addresses attached.
4. Application number(s) or patent number(s):  This document is being filed together with a new application, the execution date of the application is: May 31, 2007  There are no additional numbers attached.	
5. Send correspondence to:  Maria Parrish Tungol 5820 Fifer Drive, Suite 100 Alexandria, VA 22303	6. Total no. of applications involved: <input type="text" value="1"/>  7. Total fee (37 CFR 3.41) = \$40  A Credit Card Payment Form is enclosed.
9. Statement and signature  To the best of the knowledge and belief of the undersigned, the foregoing information is true and correct and any attached copy is a true copy of the original document.  <div style="display: flex; justify-content: space-between;"><div>Maria Parrish Tungol Attorney for Applicants Reg. No. 31,720</div><div style="text-align: center;"> Signature</div><div style="text-align: right;">May 31, 2007 Date</div></div> <div style="display: flex; justify-content: flex-end;"><div>Total Number of pages, including cover sheet, attachments, and documents: <input type="text" value="2"/></div></div>	

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PATENT  
REEL: 019425 FRAME: 0399

## ASSIGNMENT

WHEREAS, WE, Tae Uk Kim, Hee Sook Na, and Duk Hee Kim (hereafter, ASSIGNORS), citizens of REPUBLIC OF KOREA respectively residing at 332-2 Chemicals R&D Center, Gocheon-dong, Uiwang-si, Gyeonggi-do, 437-711, Republic of Korea and 27-811 Dongaldanji Apt., Bupyeong-dong, Bupyeong-gu, Incheongwangyeok-si, 403-761, Republic of Korea and 501-202 Seogwang Apt., 236-6 Hyoseong-dong, Gyeyang-gu, Incheongwangyeok-si, 407-040, Republic of Korea are the inventors of the invention in THERMOPLASTIC RESIN COMPOSITION WITH LOW COEFFICIENT OF LINEAR THERMAL EXPANSION for which we have executed an application for Letters Patent of the United States on the date by our signatures below

and WHEREAS, CHEIL INDUSTRIES INC (hereafter, ASSIGNEE), a corporation under the laws of Republic of Korea, having a place of business at 290 Gongdan-dong, Gumi-si, Gyeongsangbuk-do, 730-710, Republic of Korea is desirous of obtaining the entire right, title and interest in, to and under the said invention and the said application;

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, we, the said ASSIGNORS, have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said ASSIGNEE the entire right, title and interest in, to and under all our inventions, whether joint or sole, disclosed in the said application and in, to and under all applications filed for Letters Patent of the United States for any of said inventions and in, to and under all patents granted on the said applications;

AND WE HEREBY further covenant and agree that we will communicate to the said ASSIGNEE, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceeding, sign all lawful papers, and execute all applications and papers necessary to obtain and maintain proper patent protection on said inventions;


AND WE HEREBY authorize and request the Commissioner of Patents and Trademarks of the United States to issue all patents on the said application to the said ASSIGNEE in accordance with the terms of this instrument;

IN TESTIMONY WHEREOF, We hereunto set our hands and seals on the date set opposite our respective signatures.

Date: May 31, 2007

  
Tae Uk Kim

Date: May 31, 2007

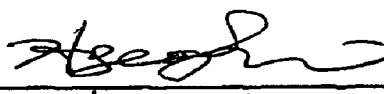
  
Hee Sook Na

Date: May 31, 2007

  
Duk Hee Kim

WITNESS:

Date: May 31, 2007

  
Hyejin Lee